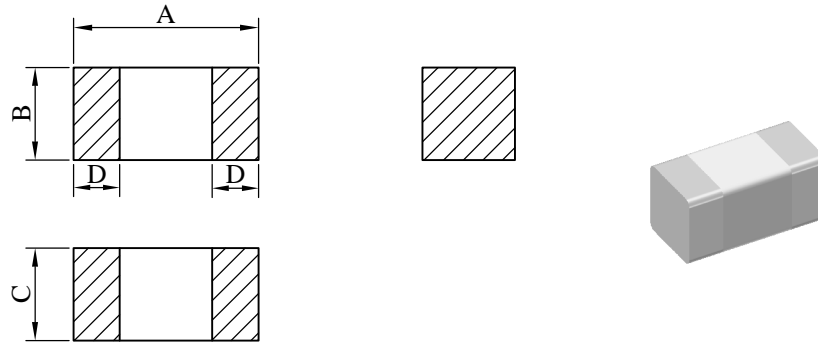


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Multilayer Chip Inductor	ABC'S DWG NO.	MH1608□□□□2□-□□□		
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I . Configuration and dimensions :



Unit : m/m

A	B	C	D
1.60 ± 0.20	0.80 ± 0.20	0.80 ± 0.20	0.30 ± 0.20

II . Materials :

- a . Body : Ceramic
- b . Internal conductor : Silver
- c . Terminal electrode : Ag / Ni / Sn
- d . Product weight : 5.4 mg (ref.)
- e . Products comply with RoHS' requirements
- f . Halogen free available.

III . General specification :

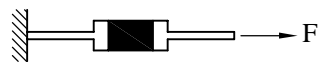
a . Storage Conditions :

Electrical Performance temp : -55°C ---- +125°C

Terminal Solderability & Packages Material temp : -10°C ---- +40°C and RH 70% max.

b . Operating temp. : -55°C ---- +125°C

c . Terminal strength :

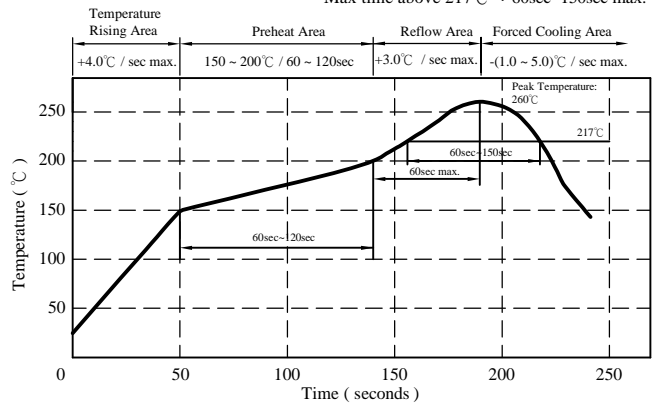


Type	F (kgf)	Time (sec)
MH1608	0.5	30±5

d . Resistance to soldering heat :

Solder temp. : 260°C
Dip time : 10 sec max.

Peak Temp : 260°C max.
Max. Peak Temp - 5°C : 30sec max.
Max time above 217°C : 60sec~150sec max.



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IV . Electrical characteristics :

DWG No.	Inductance (nH)	Q min.	L / Q Test Freq. (MHz)	SRF (GHz) min.	RDC (Ω) max.	IDC (mA) max.
MH16081N0D2□-□□□	1.0 ± 0.3	8	100	10.0	0.05	300
MH16081N2D2□-□□□	1.2 ± 0.3	8	100	10.0	0.05	300
MH16081N5D2□-□□□	1.5 ± 0.3	8	100	6.0	0.10	300
MH16081N8D2□-□□□	1.8 ± 0.3	8	100	6.0	0.10	300
MH16082N2D2□-□□□	2.2 ± 0.3	8	100	6.0	0.10	300
MH16082N7D2□-□□□	2.7 ± 0.3	10	100	6.0	0.10	300
MH16083N3D2□-□□□	3.3 ± 0.3	10	100	6.0	0.12	300
MH16083N9D2□-□□□	3.9 ± 0.3	10	100	6.0	0.14	300
MH16084N7D2□-□□□	4.7 ± 0.3	10	100	4.0	0.16	300
MH16085N6D2□-□□□	5.6 ± 0.3	10	100	4.0	0.18	300
MH16086N8J2□-□□□	6.8 ± 5%	10	100	4.0	0.22	300
MH16088N2J2□-□□□	8.2 ± 5%	10	100	3.5	0.24	300
MH160810NJ2□-□□□	10.0 ± 5%	12	100	3.4	0.26	300
MH160812NJ2□-□□□	12.0 ± 5%	12	100	2.6	0.28	300
MH160815NJ2□-□□□	15.0 ± 5%	12	100	2.3	0.32	300
MH160818NJ2□-□□□	18.0 ± 5%	12	100	2.0	0.35	300
MH160822NJ2□-□□□	22.0 ± 5%	12	100	1.6	0.40	300
MH160827NJ2□-□□□	27.0 ± 5%	12	100	1.4	0.45	300
MH160833NJ2□-□□□	33.0 ± 5%	12	100	1.2	0.55	300
MH160839NJ2□-□□□	39.0 ± 5%	12	100	1.1	0.60	300
MH160847NJ2□-□□□	47.0 ± 5%	12	100	0.9	0.70	300
MH160856NJ2□-□□□	56.0 ± 5%	12	100	0.9	0.75	300
MH160868NJ2□-□□□	68.0 ± 5%	12	100	0.7	0.85	300
MH160882NJ2□-□□□	82.0 ± 5%	12	100	0.6	0.95	300
MH1608R10J2□-□□□	100.0 ± 5%	12	100	0.6	1.00	300

1). □ : Packaging information : □ Code

2). "- □□□ " : Reference code

3). Electrical specifications at 25°C

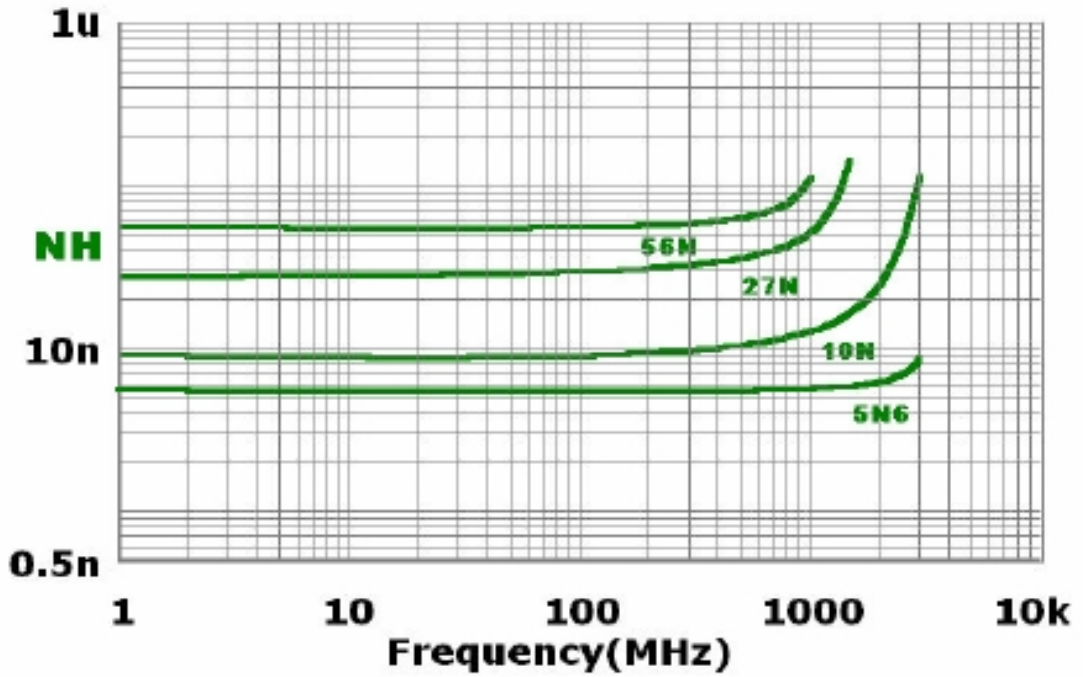
SPECIFICATION FOR APPROVAL

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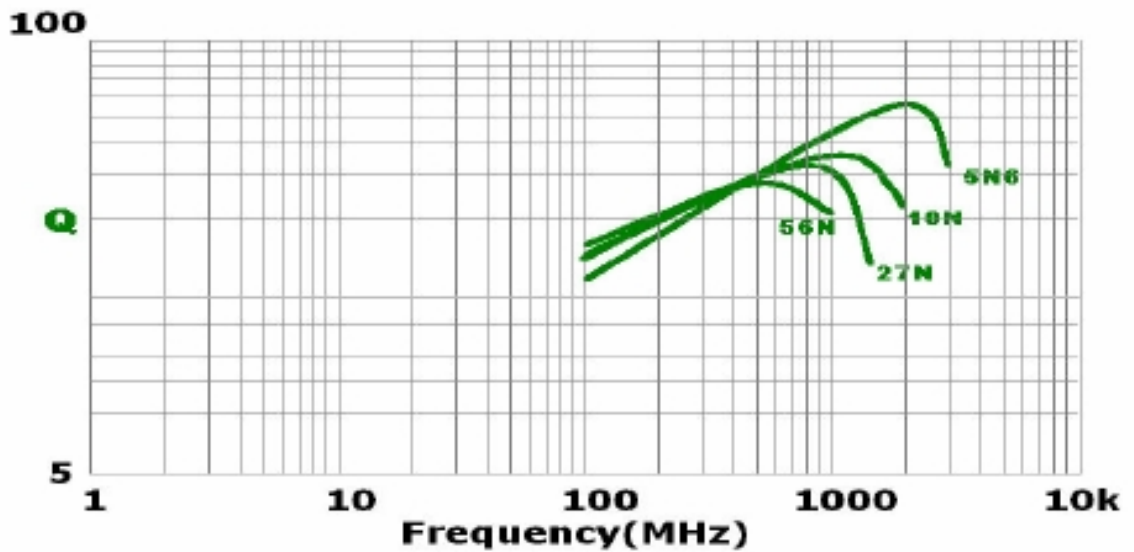
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V . L / Q VS. Freq. Curve :

INDUCTANCE VS FREQUENCY CHARACTERISTICS



Q VS FREQUENCY CHARACTERISTICS



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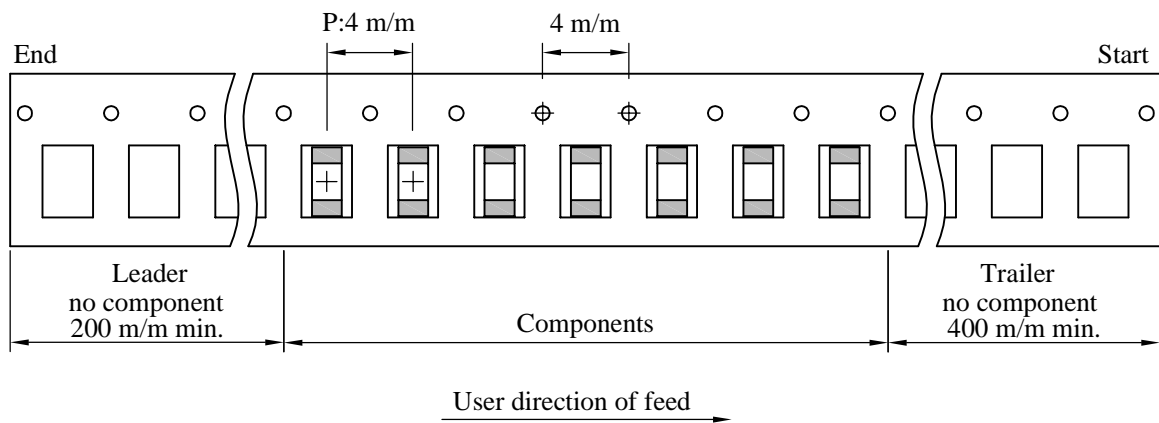
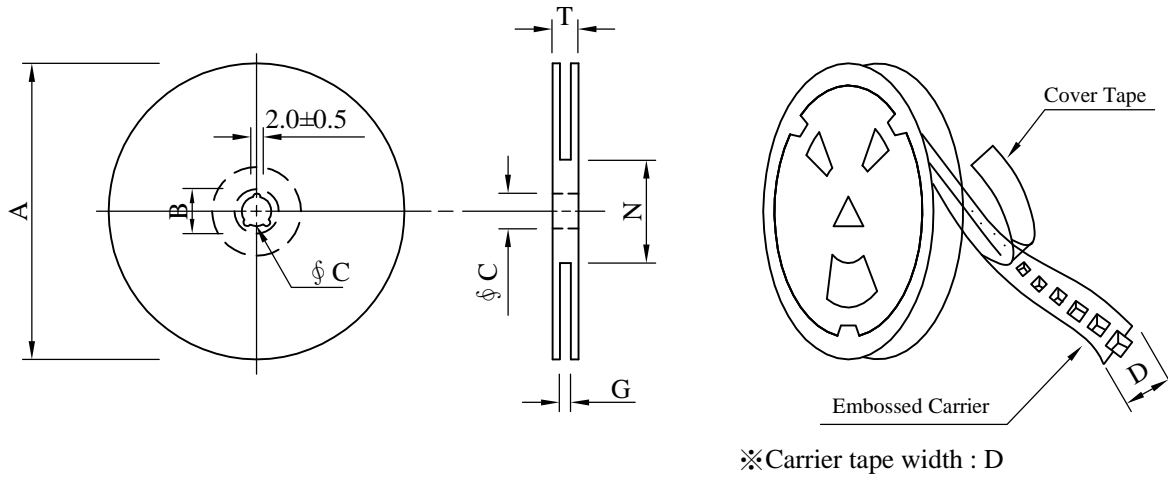
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VI . Packaging information :

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	4,000	90	07 - 08	200,000	7.0	41 x 39 x 22

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SPECIFICATION FOR APPROVAL

REF. :

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VII . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125°C 2.Time:1008 hours. 3.Measurement : After placing for 24 hours min.	1.Body: No damage 2.Inductance shall not change more than ±20%.
2.Low Temperature Exposure	JESD22-A 119	1.Temperature: -55°C 2.Time:1008 hours. 3.Measurement : After placing for 24 hours min.	1.Body: No damage 2.Inductance shall not change more than ±20%.
3.Temperature Cycling	JESD22-A 104	1.Temperature: -55°C ~ 125°C 2.Number of cycle:100 cycle 3.Dwell time:30 minutes 4.Measurement : After placing for 24 hours min.	1.Body: No damage 2.Inductance shall not change more than ±20%.
4.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature:40±5 °C 2.Time:1008 Hours 3.Humidity: 95% RH. 4.Measurement : After placing for 24 hours min.	1.Body: No damage 2.Inductance shall not change more than ±20%.
5.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-55-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	Appearance: No damage
6.Resistance To Soldering Heat Test	MIL-STD-202 Method 210	1.Solder Temp. : 265±3°C 2.Immersion time : 6±1 sec 3.Preheating : 100°C to 150°C, 1 minute. 4.Measurement : After placing for 24 hours min.	1.Appearance: No damage 2.Inductance shall not change more than ±20%.
7.Solderability Test	J-STD-002	1.Preheat : 150°C,60 seconds 2.Solder temperature : 245±5°C 3.Flux 4.Dip time : 4±1 seconds	The terminal shall be at least 90% covered with fresh solder.
8.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force: Refer to product specification. 3.Dwell time : >25 seconds.	The terminal electrode and the body shall not be damaged by the forces applied on the right conditions.
9.Board Flex	JIS-C-6429	1.Deflection speed : 1 mm/ sec 2.Amount of deflection : 2 mm 3.Span : 90 mm 4.Direction for test : Bottom of PCB 5.Holding time : 60 seconds.	1.Appearance: No damage 2.The terminal electrode and the body shall not be damaged by the forces applied on the right conditions.

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